

Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	4 X 4 X 0.85 (2.7 EP)
Lead Count	24
Terminal Finish	NiPdAu
MS Number	MS012345B

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	1.81E-02	93.70	937000	53.00	530025
Thermosets	Epoxy Resin	Proprietary	5.80E-04	3.00	30000	1.70	16970
Thermosets	Phenol Resin	Proprietary	5.80E-04	3.00	30000	1.70	16970
Other inorganic materials	Carbon Black	1333-86-4	5.80E-05	0.30	3000	0.17	1697
Subtotal			1.93E-02	100.00	1000000	56.57	565661

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.33 E-02	97.50	975000	38.89	388942
Copper & its alloys	Iron	7439-89-6	3.21 E-04	2.35	23500	0.94	9375
Copper & its alloys	Zinc	7440-66-6	1.64 E-05	0.12	1200	0.05	479
Copper & its alloys	Phosphorus	7723-14-0	4.09 E-06	0.03	300	0.01	120
Subtotal			1.36 E-02	100.00	1000000	39.89	398915

Internal / External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Nickel & its alloys	Nickel	7440-02-0	3.29 E-04	97.3	973000	0.96	9626
Precious metals	Palladium	7440-05-3	7.44 E-06	2.2	22000	0.02	218
Precious metals	Gold	7440-57-5	1.69 E-06	0.5	5000	0.00	49
Subtotal			3.38 E-04	100.00	1000000	0.99	9893

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	7.28 E-05	99.99	1000000	0.21	2128

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	6.00 E-04	100.0	1000000	1.76	17552

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.61 E-04	80.50	805000	0.47	4710
Other organic materials	Carbocyclic Acrylates	Proprietary	2.00 E-05	10.00	100000	0.06	585
Other organic materials	Bismaleimide resin	Proprietary	6.00 E-06	3.00	30000	0.02	176
Other organic materials	2-preponoic acid, 2-methyl	68586-19-6	6.00 E-06	3.00	30000	0.02	176
Others	Additive	Proprietary	6.00 E-06	3.00	30000	0.018	176
Other organic materials	Dicumyl peroxide	80-43-3	1.00 E-06	0.50	5000	0.003	29
Subtotal			2.00 E-04	100.0	1000000	0.59	5851

Package Totals	Weight (g)	3.42 E-02	Percentage (%)	100.00	PPM	1000000
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Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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Product / Package Information

Package	LFCSP -Sawn
Body Size (mm)	4 X 4 X 0.85 (2.7 EP)
Lead Count	24
Terminal Finish	100 Sn
MS Number	MS012324B

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Silica	60676-86-0	1.67E-02	93.70	937000	48.76		487569
Thermosets	Epoxy Resin	Proprietary	5.34E-04	3.00	30000	1.56		15611
Thermosets	Phenol Resin	Proprietary	5.34E-04	3.00	30000	1.56		15611
Other inorganic materials	Carbon Black	1333-86-4	5.34E-05	0.30	3000	0.16		1561
Subtotal			1.78 E-02	100.00	1000000	52.04		520351

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Copper & its alloys	Copper	7440-50-8	1.30 E-02	96.40	963989	38.04		380436
Copper & its alloys	Iron	7439-89-6	3.38 E-04	2.50	25006	0.99		9869
Copper & its alloys	Zinc	7440-66-6	8.10 E-05	0.60	6004	0.24		2369
Copper & its alloys	Phosphorus	7723-14-0	6.75 E-05	0.50	5001	0.20		1974
Subtotal			1.35 E-02	100.00	1000000	39.46		394648

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious Metals	Silver	7440-22-4	5.47 E-04	100.0	604420	1.60		15991

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Tin & its alloys	Tin	7440-31-5	9.05 E-04	100.0	1000000	2.65		26456

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Gold	7440-57-5	6.27 E-05	99.99	1000000	0.18		1833

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Gallium Arsenide	1303-00-0	1.07 E-03	100.0	1000000	3.13		31280

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	2.87 E-04	89.00	890000	0.84		8404
Thermoset	2-Butoxyethyl acetate	112-07-2	3.23 E-05	10.00	100000	0.09		944
Other organic materials	2-Propenoic acid, 3-(trimethoxysilyl)propyl ester	4369-14-6	3.23 E-06	1.00	10000	0.01		94
Subtotal			3.23 E-04	100.0	1000000	0.94		9442

Package Totals			Weight (g) 3.42 E-02			Percentage (%) 100		PPM 1000000
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